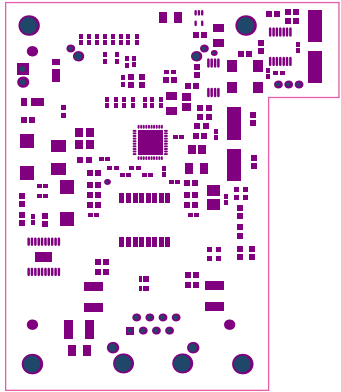
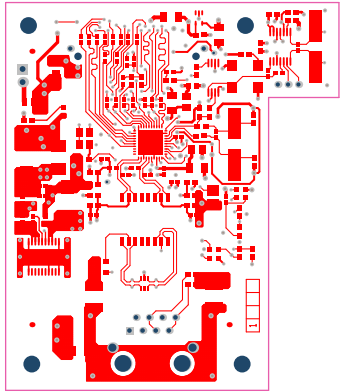


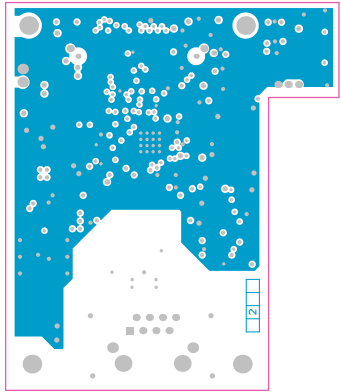
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-Q0207	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 9/22/2014 7:38:43 PM	TEXAS INSTRUMENTS	



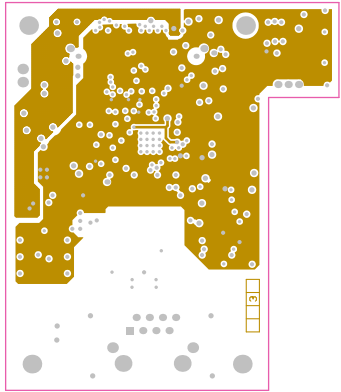
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-Q0207	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder Mask			
PLOT NAME = Top Solder Mask	GENERATED : 9/22/2014 7:38:44 PM	TEXAS INSTRUMENTS	



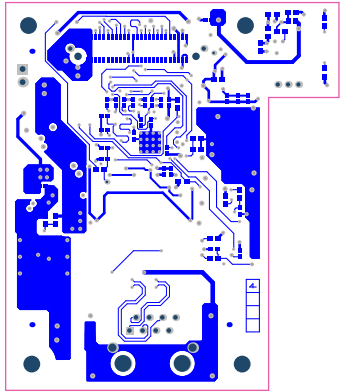
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-Q0207	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 9/22/2014 7:38:44 PM	TEXAS INSTRUMENTS	



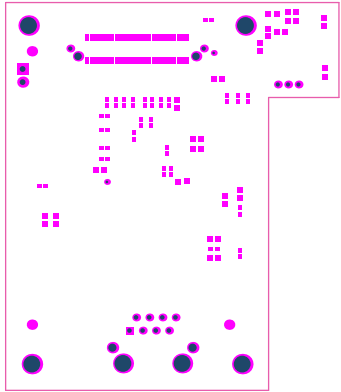
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-Q0207	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = L2_P1			
PLOT NAME = Mid Layer1	GENERATED : 9/22/2014 7:38:45 PM	TEXAS INSTRUMENTS	



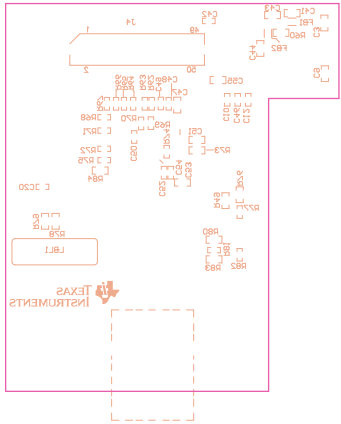
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-Q0207	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = L3_P2			
PLOT NAME = Mid Layer2	GENERATED : 9/22/2014 7:38:45 PM	TEXAS INSTRUMENTS	



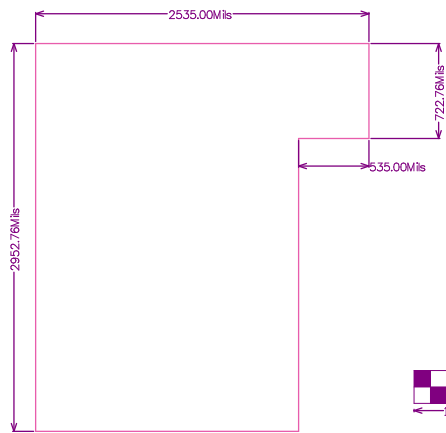
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-Q0207	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 9/22/2014 7:38:46 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-Q0207	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder Mask			
PLOT NAME = Bottom Solder Mask	GENERATED : 9/22/2014 7:38:46 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-Q0207	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 9/22/2014 7:38:46 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-Q0207	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = MI Board Outline			
PLOT NAME = Board Outline and Dimensions	GENERATED : 9/22/2014 7:38:47 PM	TEXAS INSTRUMENTS	

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